

# AK48256S / AK48256G 262,144 X 8 Bit MOS Dynamic Random Access Memory

# **DESCRIPTION**

The Accutek AK48256 high density memory modules is a random access memory organized in 256K x 8 bit words. The assembly consists of eight standard 256K x 1 DRAMs in plastic leaded chip carriers (PLCC) mounted on the front side of a printed circuit board. The module can be configured as a leadless 30 pad SIM or a leaded 30 pin SIP. This packaging approach provides a 6 to 1 density increase over standard DIP packaging.

The operation of the AK48256 is identical to eight 256K x 1 DRAMs. The data input is tied to the data output and brought out separately for each device, with common  $\overline{RAS}, \overline{CAS}$  and  $\overline{WE}$  control. This common I/O feature dictates the use of early-write cycles to prevent contention of D and Q. Since the Write-Enable ( $\overline{WE}$ ) signal must always go low before  $\overline{CAS}$  in a write cycle, Read-Write and Read-Modify-Write operation is not possible.

### **FEATURES**

- · 262,144 by 8 bit organization
- Optional 30 Pad leadless SIM (Single In-Line Module) or 30 Pin leaded SIP (Single In-Line Package)
- · JEDEC standard pinout
- <u>Each</u> device has common D and Q lines with common RAS, CAS and WE control
- · 2.8 Watt active and 180 mW standby (max)
- Operating free air temperature 0<sup>0</sup>C to 70<sup>0</sup>C
- Upward compatible with AK481024, AK581024, AK584096 and AK5816384
- Functionally and Pin compatible with AK58256A

Front View						
30-Pin SIM						
0000 0000 0000 0000 0000 0000 0000 0000 0000						
30-Pin SIP						
0000 0000 0000 0000 0000 0000 0000 0000 0000						

# PIN NOMENCLATURE

A <sub>0</sub> - A <sub>8</sub>	Address Inputs		
DQ <sub>1</sub> - DQ <sub>8</sub>	Data In / Data Out		
CAS	Column Address Strobe		
RAS	Row Address Strobe		
WE	Write Enable		
Vcc	5v Supply		
Vss	Ground		
NC	No Connect		

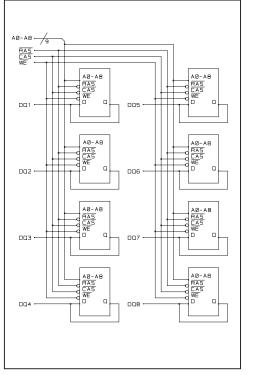
# **MODULE OPTIONS**

Leadless SIM: AK48256S
Leaded SIP: AK48256G

### **PIN ASSIGNMENT**

PIN#	SYMBOL	PIN#	SYMBOL		
1	Vcc	16	DQ5		
2	CAS	17	A8		
3	DQ!	18	NC		
4	A0	19	NC		
5	A1	20	DQ6		
6	DQ2	21	WE		
7			Vss		
8			DQ7		
9	Vss	24	NC		
10	DQ3	25	DQ8		
11	A4	26	NC		
12	A5	27	RAS		
13	13 DQ4		NC		
14	A6	29	NC		
15	A7	30	Vcc		

# **FUNCTIONAL DIAGRAM**



### ORDERING INFORMATION

# PART NUMBER CODING INTERPRETATION

Position 1 2 3 4 5 6 7 8

#### 1 Product

#### AK = Accutek Memory

- 2 Type
  - 4 = Dynamic RAM
  - 5 = CMOS Dynamic RAM
  - 6 = Static RAM

#### 3 Organization/Word Width

- $1 = by 1 \quad 16 = by 16$
- 4 = by 4 32 = by 32
- $8 = by 8 \quad 36 = by 36$
- 9 = by 9
- 4 Size/Bits Depth

#### 5 Package Type

- G = Single In-Line Package (SIP)
- S = Single In-Line Module (SIM)
- D = Dual In-Line Package (DIP)
- W = .050 inch Pitch Edge Connect
- Z = Zig-Zag In-Line Package (ZIP)

#### 6 Special Designation

- P = Page Mode
- N = Nibble Mode
- K = Static Column Mode
- W = Write Per Bit Mode
- V = Video Ram

#### 7 Separator

- = Commercial 0°C to +70°C
- M = Military Equivalent Screened (-55°C to +125°C)
- I = Industrial Temperature Tested (-45<sup>0</sup>C to +85<sup>0</sup>C)
- X = Burned In
- 8 Speed (first two significant digits)

			\···· ~		0.9		
DRAMS			SRA				
	50	=	50	nS	8	=	8 nS
	60	=	60	nS	10	=	10 nS
	70	=	70	nS	12	=	12 nS
	80	=	80	nS	15	=	15 nS

The numbers and coding on this page do not include all variations available but are show as examples of the most widely used variations. Contact Accutek if other information is required.

#### **EXAMPLES:**

### AK48256SP-10

256K x 8, 100 nSEC DRAM 30 pin SIM Configuration, Page Mode

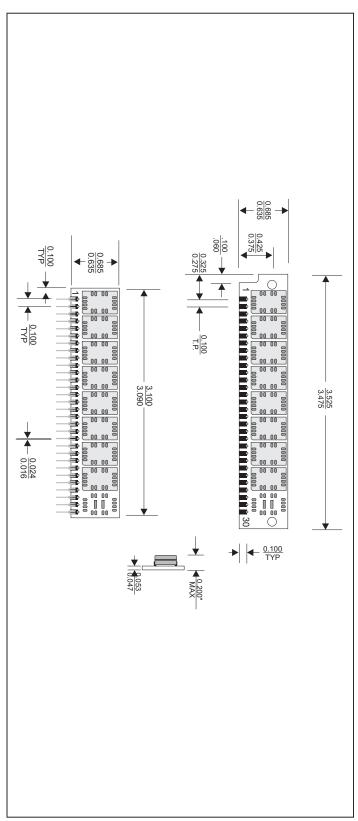
AK48256GK-80



5 NEW PASTURE ROAD NEWBURYPORT, MA 01950-4040 PHONE: 978-465-6200 FAX: 978-462-3396 Email: sales@accutekmicro.com Internet: www.accutekmicro.com

# **MECHANICAL DIMENSIONS**

Inches



Accutek reserves the right to make changes in specifications at any time and without notice. Accutek does not assume any responsibility for the use of any circuitry described; no circuit patent licenses are implied. Preliminary data sheets contain minimum and maximum limits based upon design objectives, which are subject to change upon full characterization over the specific operating conditions.